

Title (en)
PLATE-SHAPED MOLDED BODY MANUFACTURING METHOD, MOLD, AND RUNNER

Title (de)
HERSTELLUNGSVERFAHREN FÜR PLATTENFÖRMIGEN FORMKÖRPER, FORM UND ANGUSSKANAL

Title (fr)
PROCÉDÉ DE FABRICATION DE CORPS MOULÉ EN FORME DE PLAQUE, MOULE ET CANAL DE COULÉE

Publication
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Application
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Abstract (en)
[origin: EP3556533A1] The present invention provides a plate-shaped molded body manufacturing method having a step of injection-molding a liquid crystal polymer resin composition using a mold that satisfies conditions (i) to (iii) below. (i) The mold includes a cavity and a gate that is connected to the cavity, the cavity has a shape that corresponds to the plate-shaped molded body, and the gate is provided across approximately an entire width of one side of the cavity, (ii) The mold includes a runner that is connected to the gate, and the runner extends along approximately an entire width of the gate. (iii) In a cross section perpendicular to an extension direction of the runner, a shape of an inside space of the runner has a wedge-shaped portion in which a width of the inside space gradually decreases toward the gate.

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Citation (search report)
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• See references of WO 2018110646A1

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